APPROVAL SHEET

Approval Specification		Customer's Approval Certificate
TO: **Part No.:** **Customer's Part No.:**		Please return this copy as a certification of your approval **Checked & Approved by:** **Date:**

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Pages	:	6
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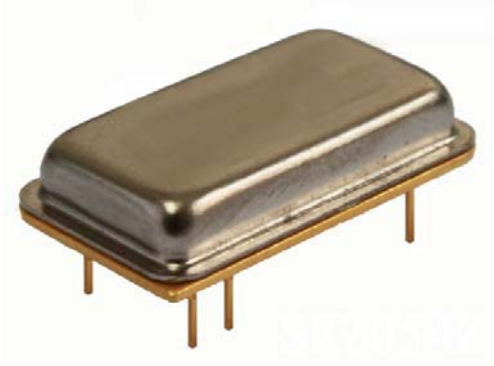
Prepared by:	梁浩
Checked by:	
Approved by:	

Application

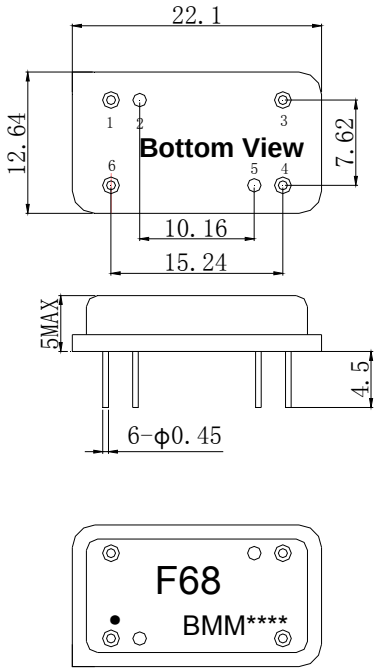
- Low -loss SAW component
- Low amplitude ripple
- Sharp rejections at both out-bands
- Passband 0.27 MHz



Features

- **RoHS** compatible
- Package size 22.1x12.64x5.00mm^3
- Package Code DIP2212
- **E**lectrostatic **S**ensitive **D**evice(**ESD)**

Package Dimensions (Unit: mm)



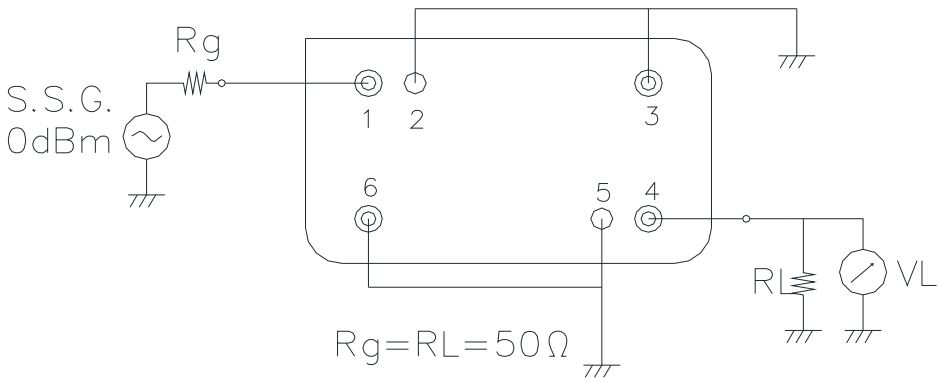
Pin Configuration

Pin No.	Description
1	Input
4	Output
2,3,5,6	Ground

Marking Description

F	SAW Filter
68	Center Frequency
●	Pin 1
BMM	Year Code & Month Code
********	Serial No.

Test Circuit(Bottom View)



Performance

Maximum Rating

Item		Value	Unit
DC Voltage	V_{DC}	3	V
Operation Temperature	T	-55 ~ +85	℃
Storage Temperature	T_{stg}	-55 ~ +125	℃
RF Power Dissipation	P	10	dBm

Electronic Characteristics

Test Temperature: 25℃±2℃

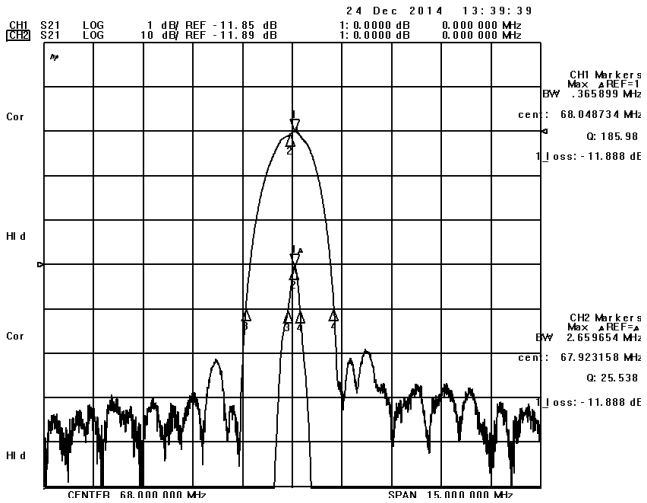
Terminating source impedance: 50Ω

Terminating load impedance: 50Ω

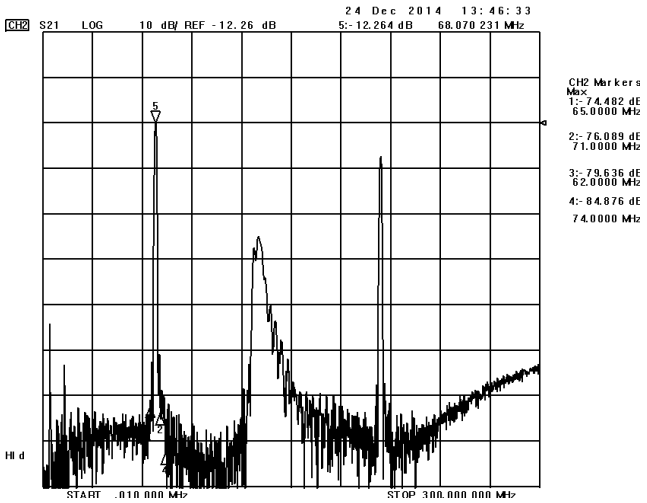
Item		Minimum	Typical	Maximum	Unit
Center Frequency	fc		68.0		MHz
Insertion Loss(min)	IL		11.9	13.0	dB
1 dB Bandwidth	BW_{1dB}	0.27	0.36		MHz
40 dB Bandwidth	BW_{40dB}	2.50	2.66	2.70	MHz
Absolute Attenuation	α				
62.00MHz		55.0	67.0		dB
65.00MHz		50.0	62.0		dB
66.00MHz		48.0	52.0		dB
70.00MHz		48.0	49.0		dB
71.00MHz		50.0	63.0		dB
74.00MHz		55.0	72.0		dB

Frequency Characteristics

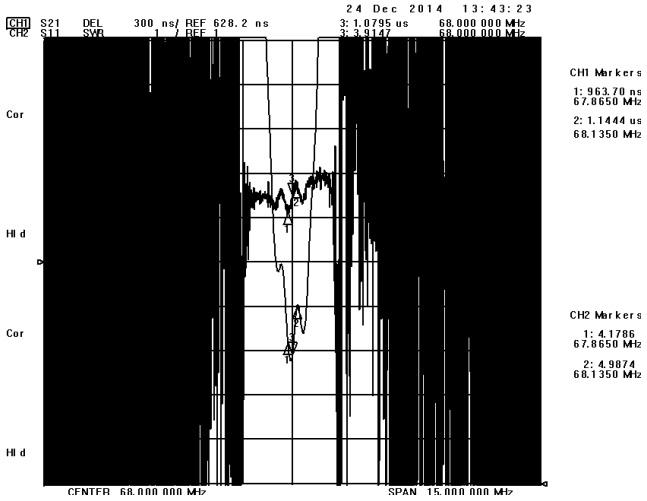
Frequency Response



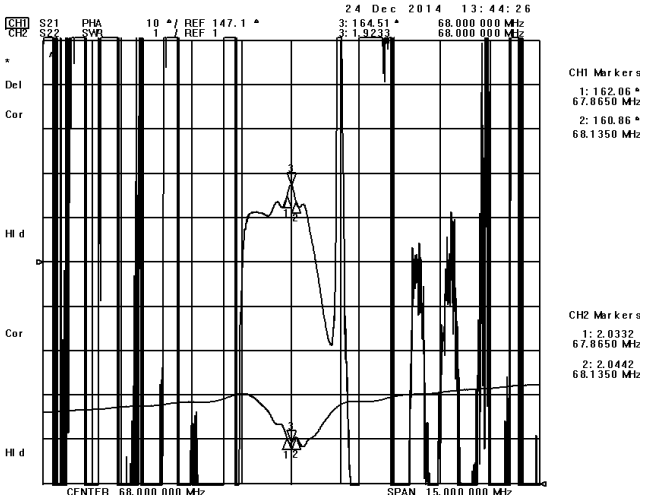
Frequency Response（wideband）



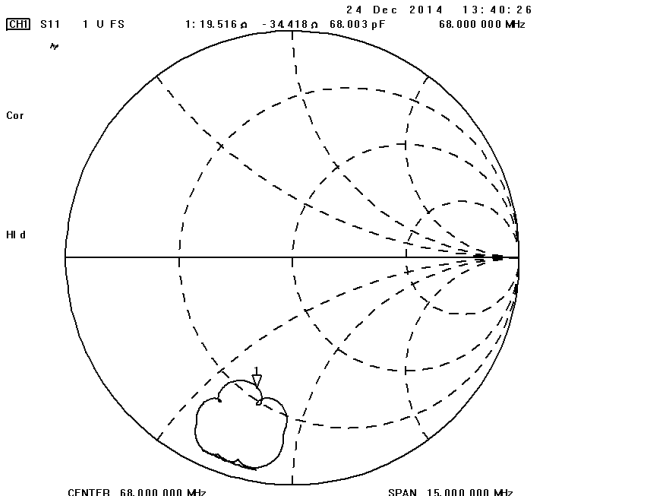
Delay Ripple & S11 VSWR



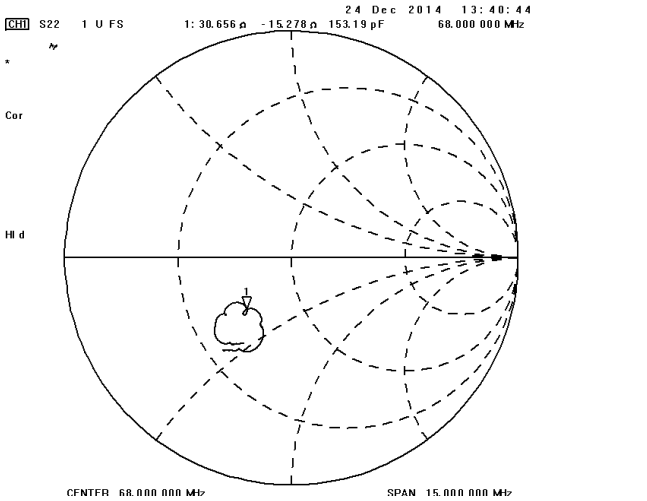
Phase Linearity & S22 VSWR



S11 Smith Chart



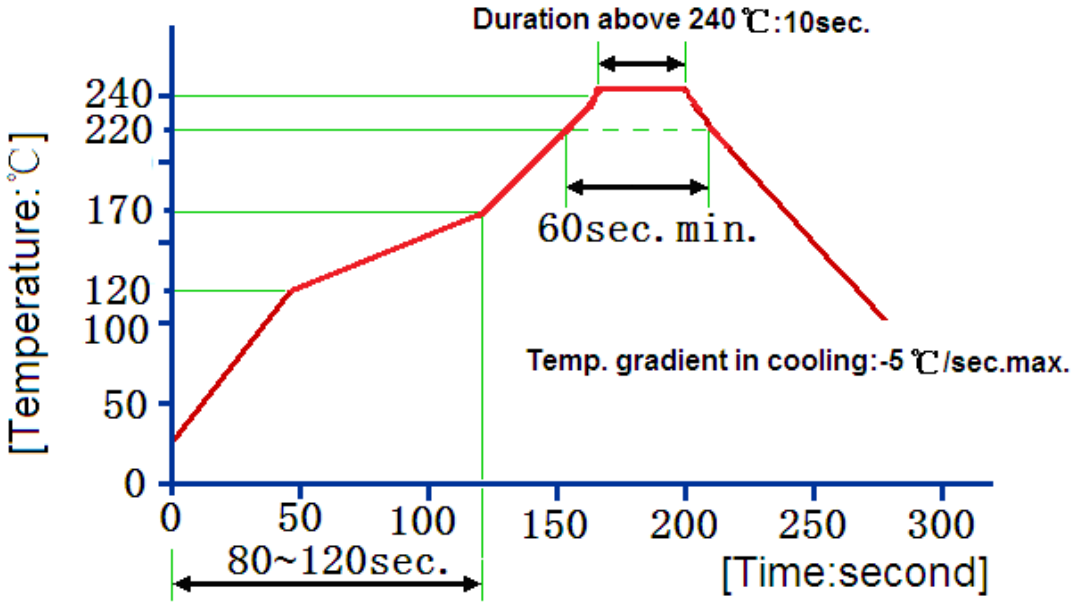
S22 Smith Chart



Reliability（The SAW components shall remain electrical performance after tests）

No.	Test item	Test condition
1	Temperature Storage	(1) Temperature: 85℃±2℃ , Duration: 250h , Recovery time: 2h±0.5h (2) Temperature: –55℃±3℃ , Duration: 250h ,Recovery time: 2h±0.5h
2	Humidity Test	Conditions: 60℃±2℃ , 90~95% RH Duration: 250h
3	Thermal Shock	Heat cycle conditions: TA=-55℃±3℃, TB=85℃±2℃, t1=t2=30min, Switch time: ≤3min, Cycle time: 100 times, Recovery time: 2h±0.5h.
4	Vibration Fatigue	Frequency of vibration: 10~55Hz Amplitude:1.5mm Directions: X,Y and Z Duration: 2h
5	Drop Test	Cycle time: 10 times Height: 1.0m
6	Solder Ability Test	Temperature: 245℃±5℃ Duration: 3.0s--5.0s Depth: DIP--2/3 , SMD--1/5
7	Resistance to Soldering Heat	(1)Thickness of PCB:1mm , Solder condition: 260℃±5℃ , Duration: 10±1s (2)Temperature of Soldering Iron: 350℃±10℃ , Duration: 3~4s , Recovery time : 2 ± 0.5h

Recommended Reflow Soldering Diagram



Reflow cycles:3 cycles max.

Notes

1. As a result of the particularity of inner structure of SAW products, it easy to be breakdown by electrostatic, so we should pay attention to **ESD protect** in the test.
2. **Static voltage** between signal load and ground may cause deterioration and destruction of the component. Please avoid static voltage.
3. **Ultrasonic cleaning** may cause deterioration and destruction of the component. Please avoid ultrasonic cleaning.
4. Only leads of component may **be soldered**. Please avoid soldering another part of component.
5. There is a close relationship between the device's performance and **matching network**. The specifications of this device are based on the test circuit shown above. L and C values may change depending on board layout. Values shown are intended as a guide only.